



High-end Power Semiconductor Manufacturer

KP2000A 1000V-1800V

Phase Control Thyristor

- High power cycling capability
- Low on-state and switching losses
- Designed for traction and industrial applications



Mean on-state current	I_{TAV}	2000 A			
Repetitive peak off-state voltage	V_{DRM}	1000 – 1800 V			
Repetitive peak reverse voltage	V_{RRM}				
Turn-off time	t_q	250 μ s			
V_{DRM}, V_{RRM}, V	1000	1200	1400	1600	1800
Voltage code	10	12	14	16	18
$T_i, ^\circ C$	– 60 – 125				

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Mean on-state current	A	2000	$T_c = 85^\circ C$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	3140	$T_c = 85^\circ C$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	44.0	$T_j = T_{j \max}$	180° half-sine wave; 50 Hz ($t_p = 10$ ms); single pulse; $V_D = V_R = 0$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μ s; $di_G/dt \geq 1$ A/ μ s
			51.0	$T_j = 25^\circ C$	
I^2t	Safety factor	$A^2 s \cdot 10^3$	47.0	$T_j = T_{j \max}$	180° half-sine wave; 60 Hz ($t_p = 8.3$ ms); single pulse; $V_D = V_R = 0$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μ s; $di_G/dt \geq 1$ A/ μ s
			54.0	$T_j = 25^\circ C$	
			9680	$T_j = T_{j \max}$	180° half-sine wave; 50 Hz ($t_p = 10$ ms); single pulse; $V_D = V_R = 0$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μ s; $di_G/dt \geq 1$ A/ μ s
			13005	$T_j = 25^\circ C$	
			9165	$T_j = T_{j \max}$	180° half-sine wave; 60 Hz ($t_p = 8.3$ ms); single pulse; $V_D = V_R = 0$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μ s; $di_G/dt \geq 1$ A/ μ s
			12100	$T_j = 25^\circ C$	
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	1000–1800	$T_{j \min} < T_j < T_{j \max}$ 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	1100–1900	$T_{j \min} < T_j < T_{j \max}$ 180° half-sine wave; 50 Hz; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	0.75 V_{DRM} 0.75 V_{RRM}	$T_j = T_{j \max}$ Gate open	

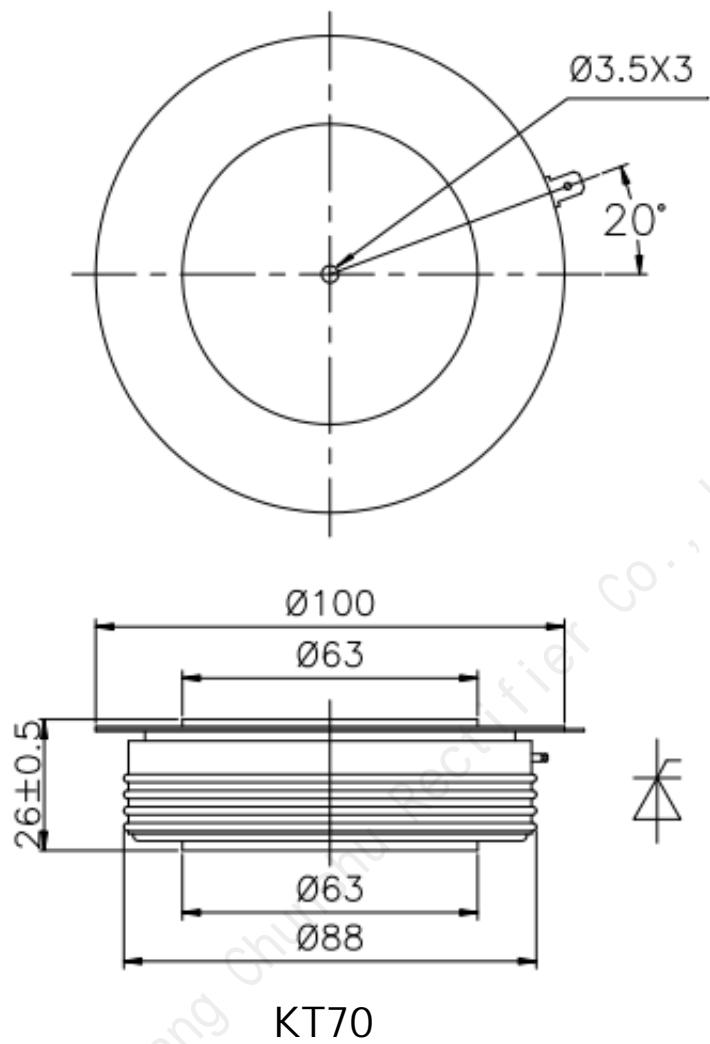
TRIGGERING				
I_{FGM}	Peak forward gate current	A	8	$T_j = T_{j \max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	5	$T_j = T_{j \max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	$A/\mu s$	630	$T_j = T_{j \max}; V_D = 0.67 V_{DRM}; I_{TM} = 2 I_{TAV};$ Gate pulse: $I_G = 2 A$; $t_{GP} = 50 \mu s$; $di_G/dt \geq 1 A/\mu s$
THERMAL				
T_{stg}	Storage temperature	$^{\circ}C$	-60 – 125	
T_j	Operating junction temperature	$^{\circ}C$	-60 – 125	
MECHANICAL				
F	Mounting force	kN	33.0 – 40.0	
a	Acceleration	m/s^2	50 100	Device unclamped Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions		
ON-STATE						
V_{TM}	Peak on-state voltage, max	V	1.65	$T_j = 25 ^{\circ}C; I_{TM} = 5000 A$		
$V_{T(TO)}$	On-state threshold voltage, max	V	0.90	$T_j = T_{j \max};$		
r_T	On-state slope resistance, max	$m\Omega$	0.140	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$		
I_L	Latching current, max	mA	1500	$T_j = 25 ^{\circ}C; V_D = 12 V;$ Gate pulse: $I_G = 2 A$; $t_{GP} = 50 \mu s$; $di_G/dt \geq 1 A/\mu s$		
I_H	Holding current, max	mA	300	$T_j = 25 ^{\circ}C;$ $V_D = 12 V$; Gate open		
BLOCKING						
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	200	$T_j = T_{j \max};$ $V_D = V_{DRM}; V_R = V_{RRM}$		
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	$V/\mu s$	1000	$T_j = T_{j \max};$ $V_D = 0.67 V_{DRM}$; Gate open		
TRIGGERING						
V_{GT}	Gate trigger direct voltage, max	V	3.00 2.00	$T_j = 25 ^{\circ}C$ $T_j = T_{j \max}$	$V_D = 12 V; I_D = 3 A;$ Direct gate current	
I_{GT}	Gate trigger direct current, max	mA	300 200	$T_j = 25 ^{\circ}C$ $T_j = T_{j \max}$		
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j = T_{j \max};$ $V_D = 0.67 V_{DRM}$;		
I_{GD}	Gate non-trigger direct current, min	mA	15.00	Direct gate current		
SWITCHING						
t_{gd}	Delay time	μs	4.00	$T_j = 25 ^{\circ}C; V_D = 0.4 V_{DRM}; I_{TM} = I_{TAV};$ Gate pulse: $I_G = 2 A$; $t_{GP} = 50 \mu s$; $di_G/dt \geq 1 A/\mu s$		
t_q	Turn-off time ²⁾ , max	μs	250	$dv_D/dt = 50 V/\mu s; T_j = T_{j \max}; I_{TM} = 2000 A;$ $di_R/dt = -10 A/\mu s; V_R = 100 V;$ $V_D = 0.67 V_{DRM}$;		

THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.0100	Direct current	Double side cooled
R_{thjc-A}			0.0220		Anode side cooled
R_{thjc-K}			0.0180		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.0030	Direct current	
MECHANICAL					
W	Weight, typ	g	1000		
D_s	Surface creepage distance	mm (inch)	36.50 (1.437)		
D_a	Air strike distance	mm (inch)	16.5 (0.650)		

OVERALL DIMENSIONS



All dimensions in millimeters